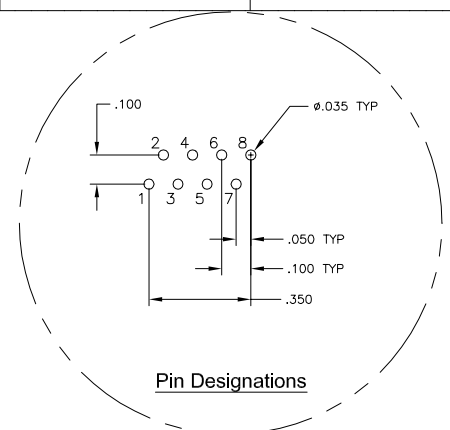
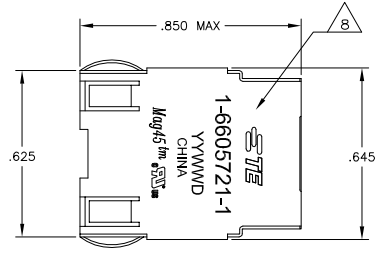
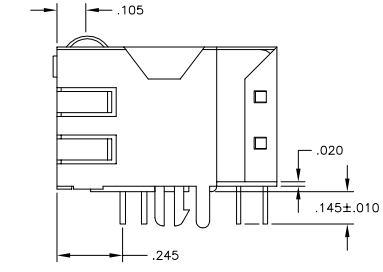
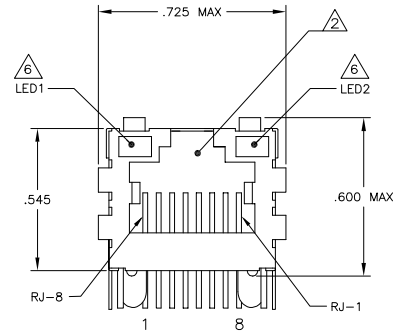


MECHANICAL:

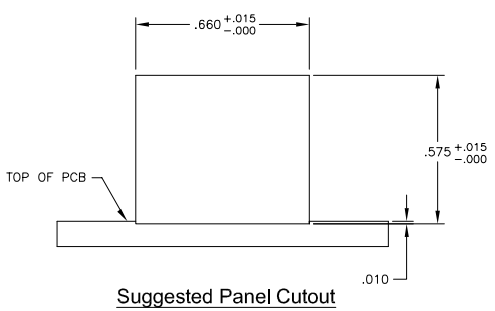


Pin Designations

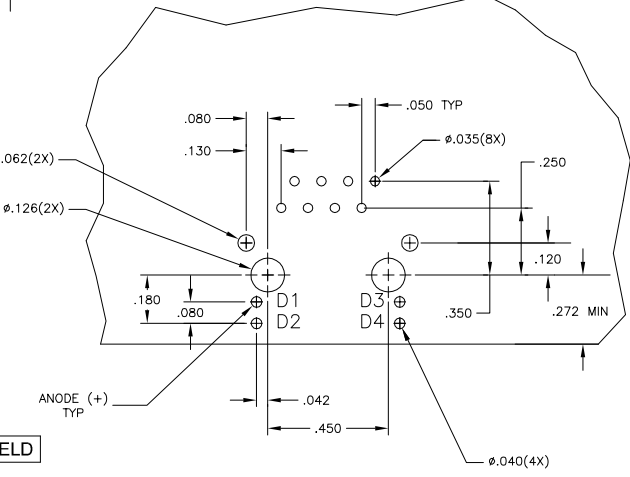
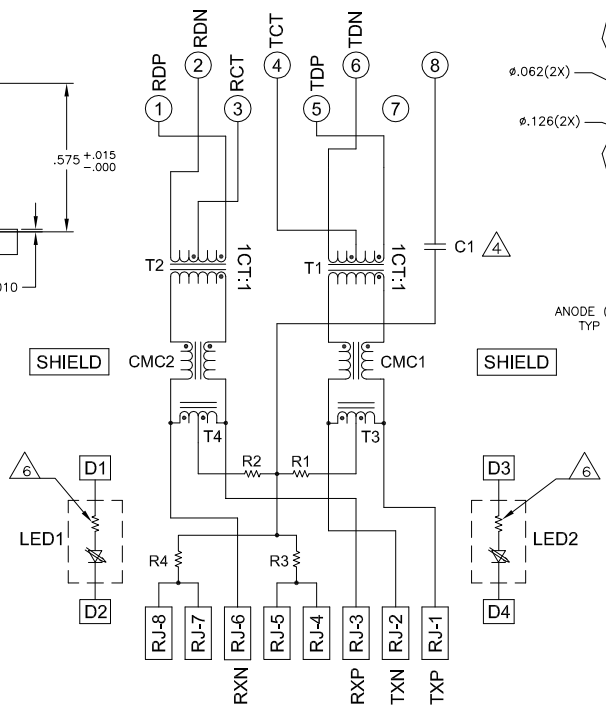


- REVISIONS**
- | REV | PER | ECO | DESCRIPTION | DATE | BY | APP |
|-----|---------|---------------|-------------|-----------|----|-----|
| B | REV PER | ECO-08-017726 | | 03JUL2008 | QL | TX |
| B1 | REV PER | ECO-10-000444 | | 20JAN2010 | KK | HMR |
| C | ECO | -11-015766 | | 30MAY2011 | EL | LR |
- MATERIALS:**
- HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.
 - SOLDERTAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**
- IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

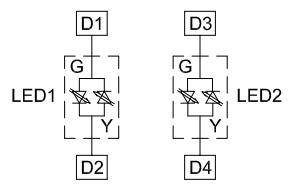
715 SERIES MAGNETIC CIRCUIT



Suggested Panel Cutout



Suggested PCB Layout (Component Side)



LED Configuration FOR 6605721-6 ONLY

C1 = 1000 pF, 2kV DECOUPLING CAPACITOR
R1-R4 = 75 OHMS, 1/16W, 5% RESISTORS

- C1 IS AN OPTIONAL. IF NO CAPACITOR, TRACE IS CONTINUOUS.**
- 5. OPERATING TEMPERATURE: FROM 0° - +70°C**
- THE 250 OHM LED RESISTORS ARE OPTIONAL, PLEASE SEE CHART FOR PRESENCE OR ABSENCE OF LED RESISTORS. IF THE LED WITHOUT 250 OHM RESISTORS, LED IS DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA.**
- LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ IF=20mA**
FORWARD VOLTAGE (VF): GREEN 2.2V TYP. @ IF=20mA
DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ IF=20mA
FORWARD VOLTAGE (VF): YELLOW 2.1V TYP. @ IF=20mA
DOMINANT WAVELENGTH (λD): ORANGE 605 nm TYP. @ IF=20mA
FORWARD VOLTAGE (VF): ORANGE 2.05V TYP. @ IF=20mA
- IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.**
- LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ VF=5V**
FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ VF=5V
FORWARD CURRENT (IF): YELLOW 13 mA TYP. @ VF=5V
- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORTS AUTO-MDI/MDIX.**
- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.**
- 9. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 265°C, 10SECONDS MAX.**
- OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI**

NO	YES	GREEN	YELLOW	5-6605721-8
YES	YES	YELLOW	GREEN	5-6605721-2
YES	YES	GREEN	YELLOW	5-6605721-1
NO	NO	GREEN/YELLOW	GREEN/YELLOW	6605721-6

LED RESISTOR (6) **DECOUPLING CAPACITOR** (A) **LED1** (A) **LED2** (A) **PART NUMBER**

THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 11MAR01. Dwg. No. ATTADIA - 11MAR01. CHG. NO. FAROLE 11MAR01.

STE TE Connectivity

DIMENSIONS: INCHES. DIMENSIONS: MILLIMETERS. PRODUCT SPEC: 108-2100. APPLICATION SPEC: RESTRICTED TO. MATERIAL: FINISH: WEIGHT: A1 00779 C=6605721. SCALE: NTS. SHEET 1 OF 1. REV C.